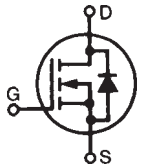
IXYS

Polar3™ HiPerFET™ Power MOSFET

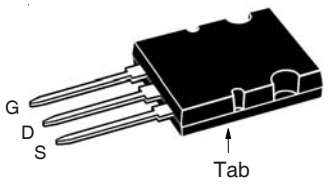
IXFB132N50P3

V_{DSS} = 500V
I_{D25} = 132A
$R_{DS(on)}$ ≤ 39mΩ
t_{rr} ≤ 250ns

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Rectifier



PLUS264™



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	500	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	500	V
V_{GSS}	Continuous	±30	V
V_{GSM}	Transient	±40	V
I_{D25}	T_C = 25°C	132	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	330	A
I_A	T_C = 25°C	66	A
E_{AS}	T_C = 25°C	2	J
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	35	V/ns
P_D	T_C = 25°C	1890	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
F_C	Mounting Force	30..120/6.7..27	N/lb
Weight		10	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	500			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8mA	3.0		5.0	V
I_{GSS}	V_{GS} = ±30V, V_{DS} = 0V			±200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			50	μA
	T_J = 125°C			3	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{DSS}$, Note 1			39	mΩ

Features

- Avalanche Rated
- Low Package Inductance
- Fast Intrinsic Rectifier
- Low $R_{DS(on)}$ and Q_G

Advantages

- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- Uninterrupted Power Supplies
- AC Motor Drives
- High Speed Power Switching Applications

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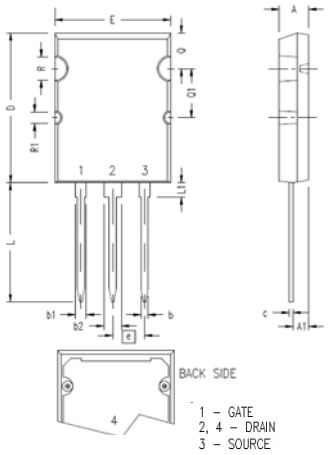
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 60A, Note 1	68	110		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		18.6		nF
C_{oss}			1710		pF
C_{rss}			12		pF
R_{Gi}	Gate Input Resistance		1.16		Ω
$t_{d(on)}$	**Resistive Switching Times**		42		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{DSS}		18		ns
$t_{d(off)}$	R_G = 1Ω (External)		90		ns
t_f			15		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{DSS}		267		nC
Q_{gs}			95		nC
Q_{gd}			63		nC
R_{thJC}				0.066	°C/W
R_{thCS}			0.13		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			132	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			530	A
V_{SD}	I_F = 100A, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 66A, -di/dt = 100A/μs			250	ns
Q_{RM}	V_R = 100V, V_{GS} = 0V		1.9		μC
I_{RM}			16.4		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

PLUS264™ (IXFB) Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215 BSC		5.46 BSC	
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,860,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ T_J = 25ºC

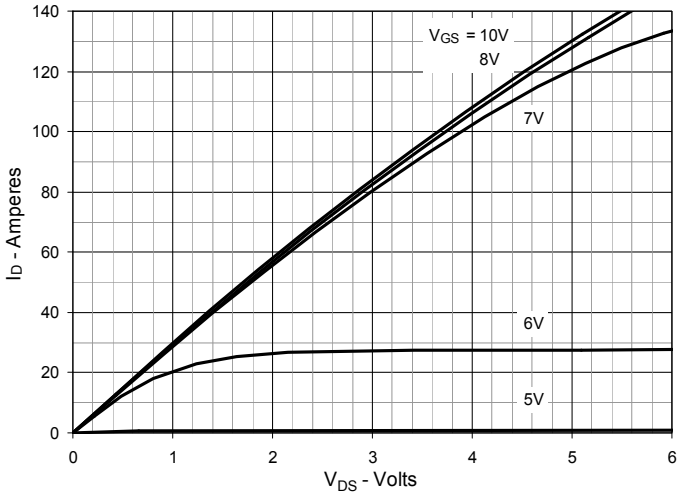


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

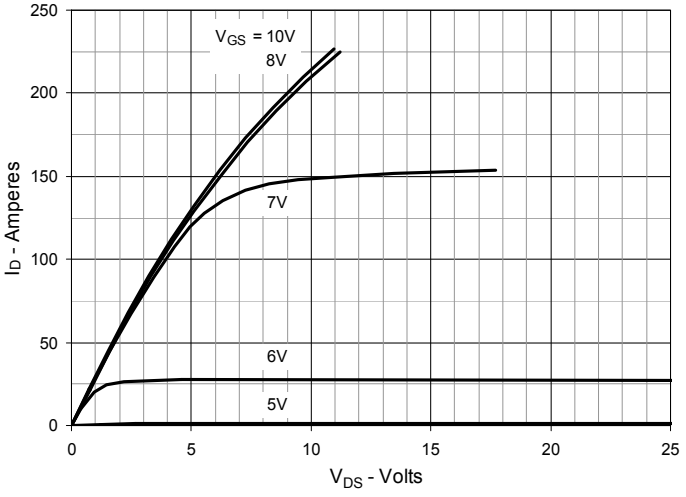


Fig. 3. Output Characteristics @ T_J = 125ºC

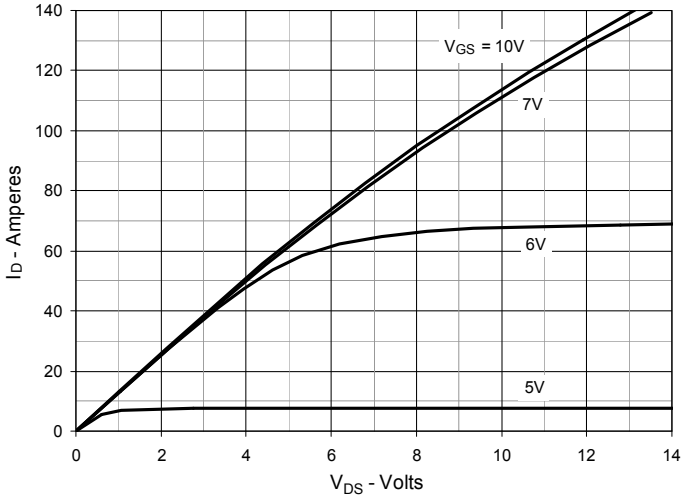


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 66A Value vs. Junction Temperature

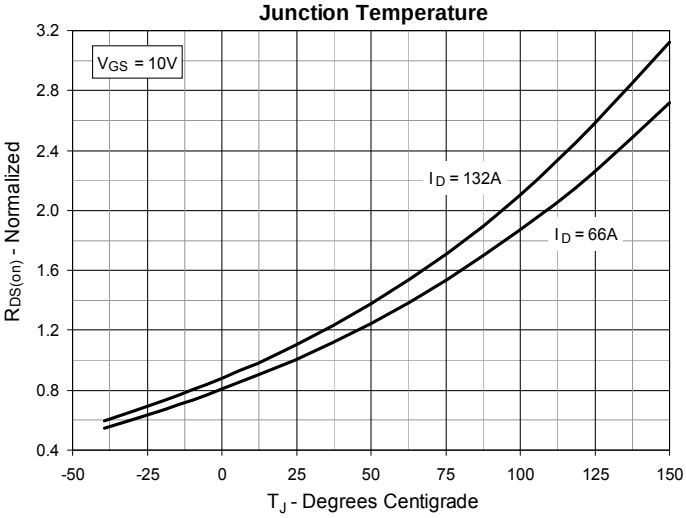


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 66A Value vs. Drain Current

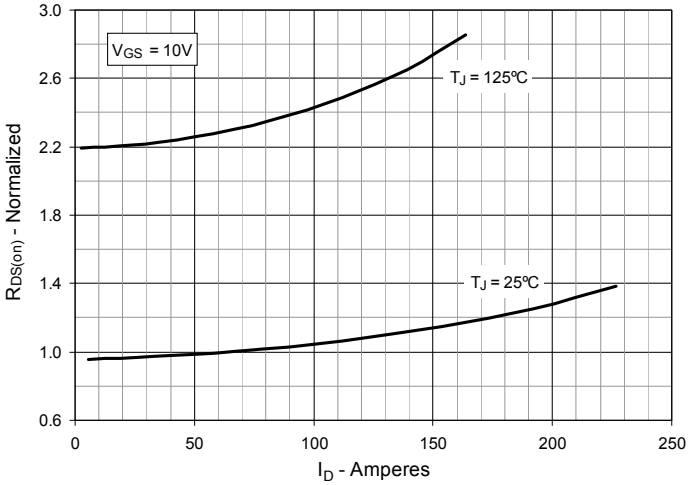
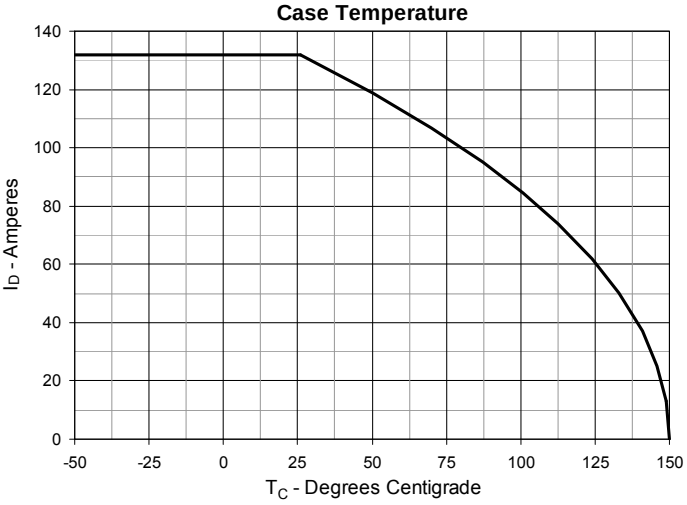


Fig. 6. Maximum Drain Current vs. Case Temperature



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Fig. 7. Input Admittance

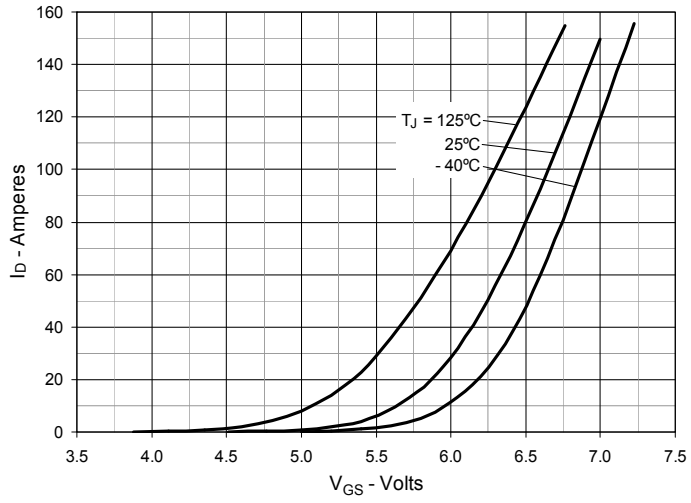


Fig. 8. Transconductance

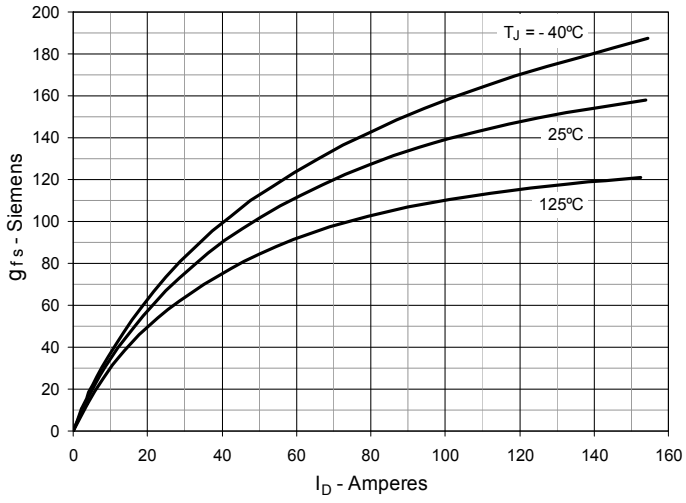


Fig. 9. Forward Voltage Drop of Intrinsic Diode

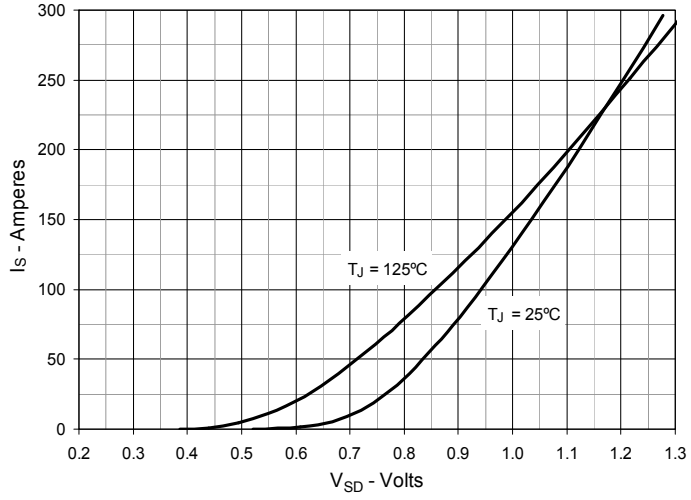


Fig. 10. Gate Charge

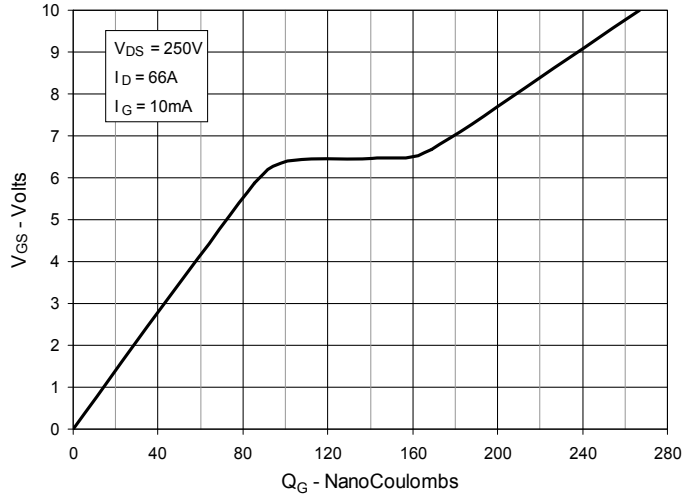


Fig. 11. Capacitance

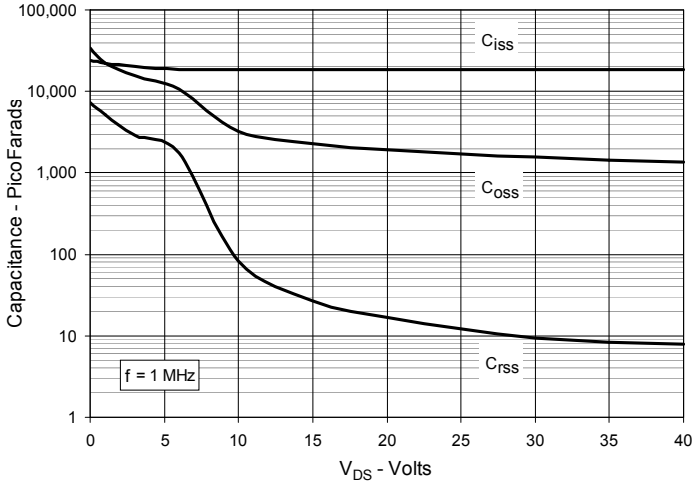
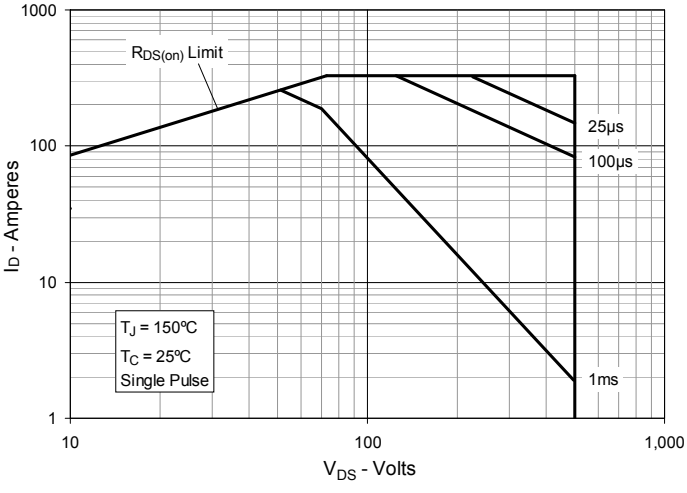


Fig. 12. Forward-Bias Safe Operating Area



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Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

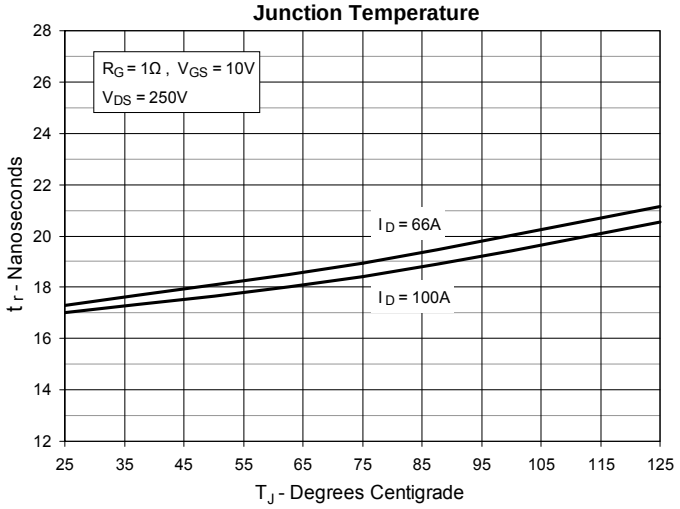


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

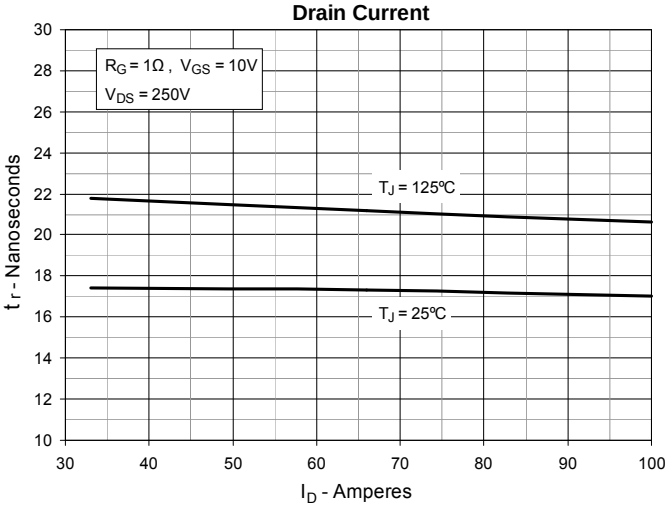


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

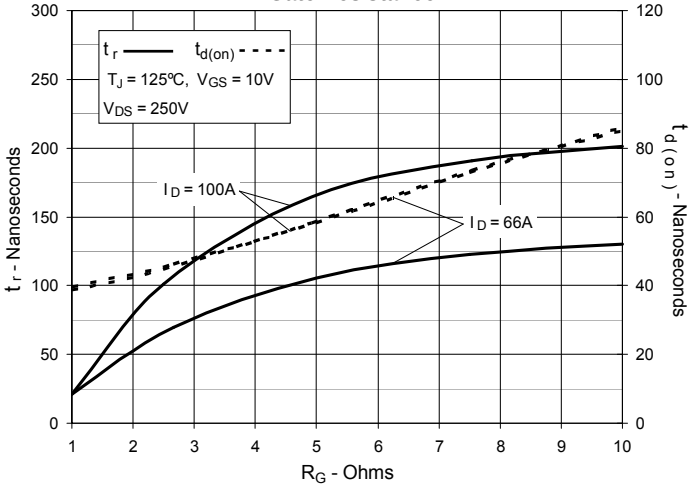


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

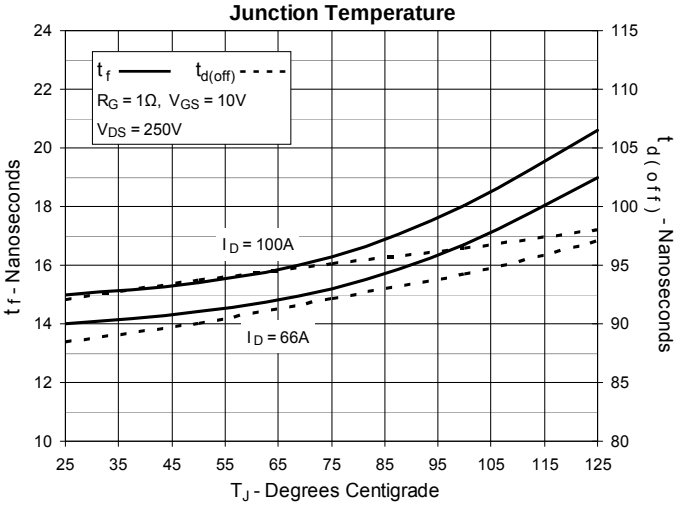


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

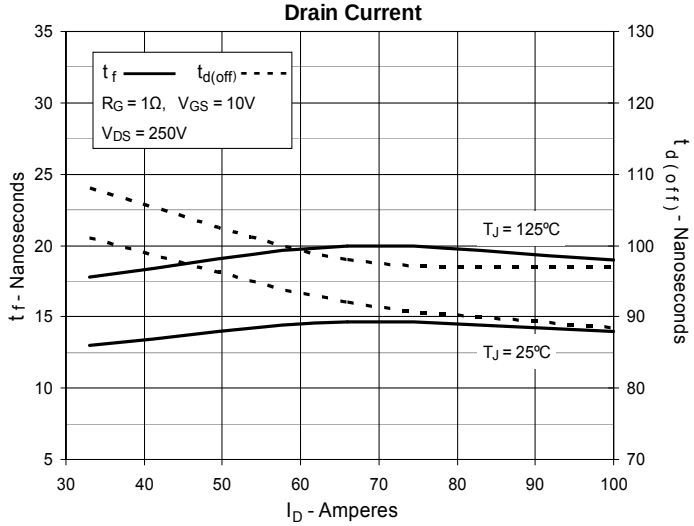
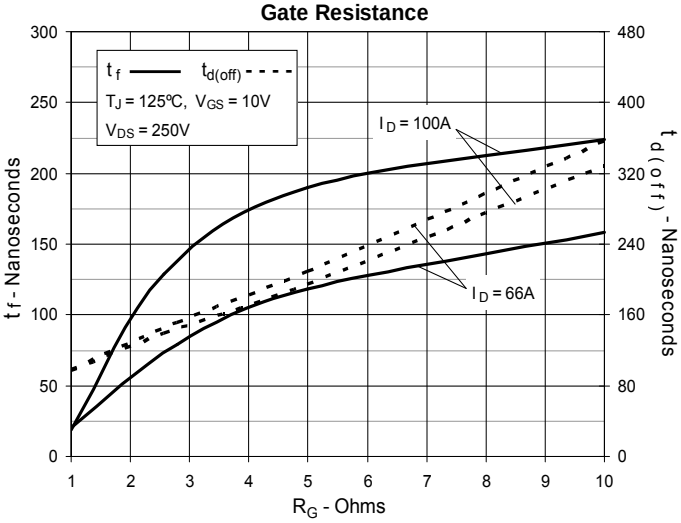


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



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Fig. 19. Maximum Transient Thermal Impedance

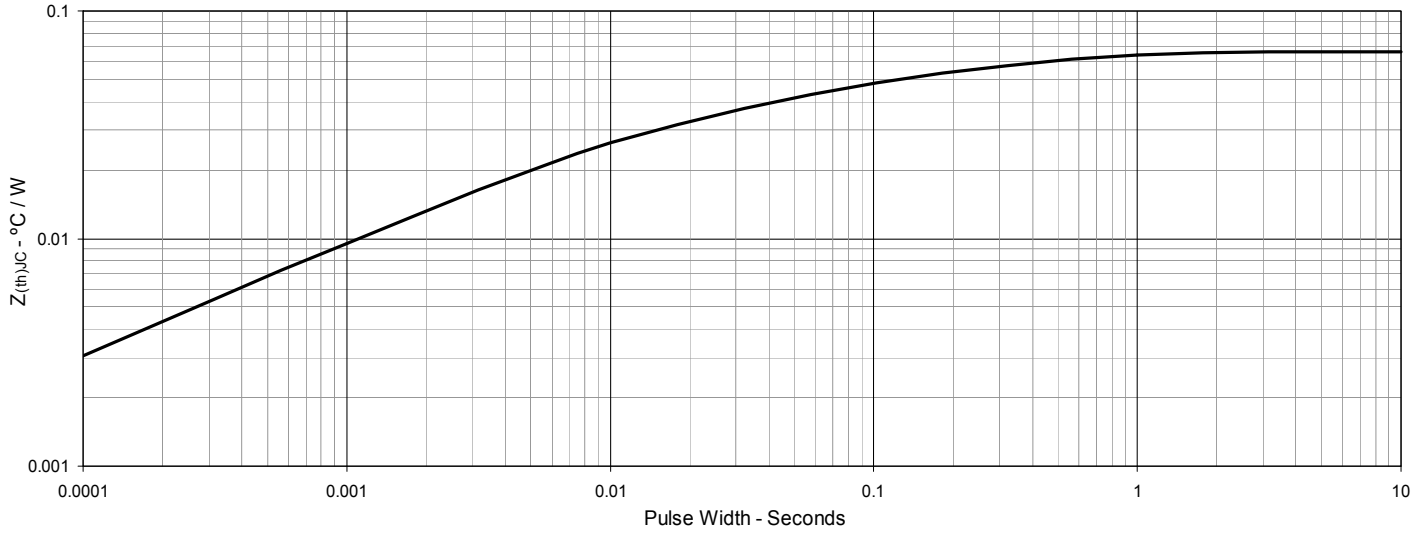
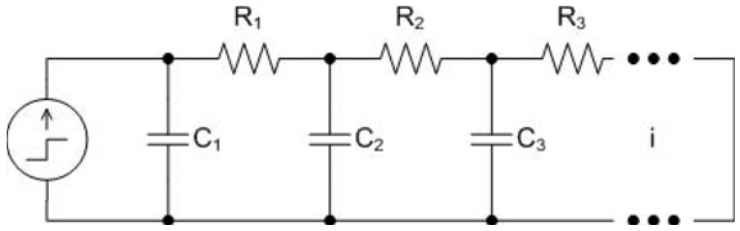


Fig. 20. Cauer Thermal Network



i	Ri (°C/W)	Ci (J/°C)
1	0.0011707	0.0031990
2	0.0252980	0.0449880
3	0.0280620	0.7284100
4	0.0091690	



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